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TITLE: SENSORCHIPPAK, 4 I/O	DOCUMENT NO: 98ASB13355C	REV: D
	STANDARD: NON-JEDEC	
	SOT1843-1	10 MAY 2017



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION: INCH.
3. 423A-01 AND -02 OBSOLETE. NEW STANDARD 423A-03.

STYLE 1:

- PIN 1. V<sub>CC</sub>  
 2. +OUT  
 3. -OUT  
 4. GROUND

DIM	MILLIMETERS		INCHES		DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	6.10	6.60	0.240	0.260	AB	0.38	0.89	0.015	0.035
B	8.89	9.40	0.350	0.370	AC	3.05	4.45	0.120	0.175
C	3.56	3.81	0.140	0.150	AD	2.54	2.92	0.100	0.115
D1	0.30	0.51	0.012	0.020					
D2	0.36	0.56	0.014	0.022					
E	2.24	2.59	0.088	0.102					
F	3.12	3.25	0.123	0.128					
G	1.14	1.40	0.045	0.055					
H	0.94	1.19	0.037	0.047					
J	0.18	0.28	0.007	0.011					
K	3.05	3.56	0.120	0.140					
L	2.41	2.67	0.095	0.105					
M	4.19	4.45	0.165	0.175					
N	5.66	6.07	0.223	0.239					
V	2.67	2.92	0.105	0.115					
AA	2.41	2.72	0.095	0.107					

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